



<b>ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SOT-923</b>					
<b>STRESS</b>	<b>SAMPLE SIZE</b>	<b>DEVICE HR./CYC</b>	<b>CONDITION</b>	<b>TOTAL FAILS</b>	<b>FAIL PERCENTAGE</b>
BOND INT	360	180 000	200 °C + N2	0	0.00
HAST	644	64 400	130 °C, 85 % RH	0	0.00
Pressure Pot	220	21 120	121°, 15 PSIG	0	0.00
Solderability	150	3600	883 M2003	0	0.00
Temp. Cycle	165	165 000	- 65 °C to 150 °C	0	0.00